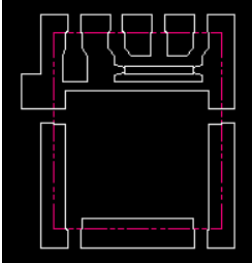
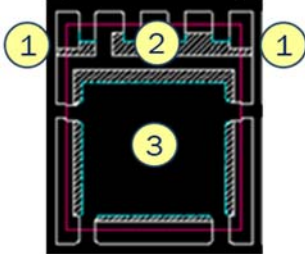




Title of Change:	Wafer Fab Transfer for Trench 6 MOSFET Technology to Global Foundries in New York, US.
Proposed Changed Material First Ship Date:	27 Dec 2021 or earlier if approved by customer
Current Material Last Order Date:	27 Jul 2021 <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>
Current Material Last Delivery Date:	26 Dec 2021 <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>
Product Category:	Active components – Discrete components
Contact information:	Contact your local ON Semiconductor Sales Office or Ammar.Anuar@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office to place sample order or PCN.samples@onsemi.com Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Robert.Baran@onsemi.com
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 12 months prior to implementation of the change. In case of questions, contact PCN.Support@onsemi.com
Change Category	
Category	Type of Change
Packing/Shipping	Dry pack requirements change
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor New wafer diameter
Process - Assembly	Move of all or part of assembly to a different location/site/subcontractor Change in process technology (e.g. plating) Change in leadframe dimensions
Description and Purpose:	
<p>This Product Change Notification is intended to increase capacity for ON's automotive 30V and 40V Trench 6 MOSFET technology products by transferring wafer fabrication for these products to the Global Foundries Fab located in New York, US.</p> <p>The changes include transferring wafer fabrication, back grind and back metal, to Global Foundries, and utilizing 300mm instead of 200mm diameter wafers. And while the assembly location remains unchanged (at ON Semiconductor, Seremban, Malaysia), wafer saw and die attach tooling are being updated to accommodate 300mm wafers. In addition, the Wetable Flank leadframe design and plating process are being enhanced, as tabulated below, in order to improve the sidewall plating and the elimination of Dry Pack.</p> <p>There is no change to the orderable part number.</p> <p>There is no product marking change as a result of this change.</p>	

	Before Change	After Change
Wafer Fabrication Site	ON Aizu, Japan ON Gresham, US	<u>Global Foundries, US</u>
Wafer Diameter	200mm (existing sites)	300mm (Global Foundries)
Wafer Probe Site	ON Seremban, Malaysia	<u>Global Foundries, US</u>
Back Grind, Back Metal Site	ON ISMF, Malaysia	<u>Global Foundries, US</u>
Wettable Flank Plating Site	Metek, Malaysia (Sub-con)	ON Seremban, Malaysia
Lead Frame design	<ol style="list-style-type: none"> 1. No tie bar connect to the gate and source lead 2. Upset lead design 3. Standard flag size 	<ol style="list-style-type: none"> 1. Additional tie bar connect to gate and source lead 2. Flat lead design 3. Larger flag size 
Clip Design	Standard	Dimension change on downset depth of the clip (due to change from upset lead to flat lead design)
Sidewall Plating Method	Electroless SN plating	Electrolytic SN plating
Packing	Drypack (MSL 1)	No Drypack (MSL 1)
Case Outline	Sharing with non-wettable flank	New case outline
Reason / Motivation for Change:	Source/Supply/Capacity Changes Process/Materials Change	
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	<p>The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded.</p> <p>No anticipated impacts.</p>	
Sites Affected:		
ON Semiconductor Sites	External Foundry/Subcon Sites	
On Semiconductor Gresham, United States	GlobalFoundries, Fab 10, New York, US	
ON Semiconductor Aizu, Japan	Metek Seremban, Malaysia (Subcon)	
ON Semiconductor Seremban, Malaysia		
Marking of Parts/ Traceability of Change:	Material will be traceable with ONs lot trace code & tracking	

**Reliability Data Summary:****(QV4) NVMF55C404NLT1G**

RMS: 66099 & 67566

PACKAGE: SO8FL-HE

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Ta=150°C, 100% max rated Vds	2016 hrs
HTGB	JESD22-A108	Ta= 150°C, 100% max rated Vgss	2016 hrs
HTSL	JESD22-A103	Ta= 150°C	2016 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off =2 min	30000 cyc
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL1 @ 260°C	
RSH	JESD22- B106	Ta = 265C, 10 sec	

(QV3) NVMF55C604NLWFT1G

RMS: 67657

PACKAGE: SO8FL-HE

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Ta=150°C, 100% max rated Vds	2016 hrs
HTGB	JESD22-A108	Ta= 150°C, 100% max rated Vgss	2016 hrs
HTSL	JESD22-A103	Ta= 150°C	2016 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off =2 min	30000 cyc
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
PC	J-STD-020 JESD-A113	MSL1 @ 260°C	
AC	JESD22-A102	121°C, 100% RH, 15 PSIG	96 hrs
RSH	JESD22- B106	Ta = 265C, 10 sec	
SD	J STD 002	Ta=245C, 5 sec	

(QV5) NVTF55C680NLTAG

RMS: 66103

PACKAGE: u8FL

Test	Specification	Condition	Interval
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL1 @ 260°C	

**(QV5) NVMF55C680NLTAG**

RMS: 66103

PACKAGE: u8FL

Test	Specification	Condition	Interval
HTGB	JESD22-A108	Ta= _150°C, 100% max rated Vgss	2016 hrs

Estimated date for qualification completion: 27 November 2020

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
NVMF54C05NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C423NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C456NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C456NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C456NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C456NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C456NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C460NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C460NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C460NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C460NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C460NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G



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NVTF55C453NLWFTAG	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G, NVTF55C680NLTAG
NVTF55C466NLWFTAG	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G, NVTF55C680NLTAG
NVMF54C03NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF54C03NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF54C05NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF54C302NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVTF54C05NWFTAG	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G, NVTF55C680NLTAG
NVTF54C13NWFTAG	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G, NVTF55C680NLTAG
NVTF54C13NWFTWG	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G, NVTF55C680NLTAG
NVMF54C01NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF54C01NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C404NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C404NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C404NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C404NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C404NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C404NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C404NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C404NWFT1G-K	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C404NWFT1G-M	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C404NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C404NWFT3G-K	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C410NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C410NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C410NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C410NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C410NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C410NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G



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NVMF55C410NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C410NWFT1G-M	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C410NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C423NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C423NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C423NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C426NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C426NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C426NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C426NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C426NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G



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NVMF55C450NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G

Japanese translation of the notification starts here.
通知の日本語訳はここから始まります。

Note: The Japanese version is for reference only. In case of any differences between the English and Japanese version, the English version shall control.

注：日本語版は参照用です。英語版と日本語版の違いがある場合は、英語版が優先されます。



初回製品 / プロセス変更通知

文書番号# : IPCN22966ZD

発行日: 13 Aug 2020

変更件名:	グローバルファンドリー(ニューヨーク、米国)にて Trench 6 MOSFET テクノロジー製品のウェハー工場生産能力拡大
初回出荷予定日:	27 Dec 2021 またはお客様からの承認が得られた場合はそれ以前
現在の材料の最終注文日:	27 Jul 2021 既存品の最終注文日以降の注文は、この PCN に記載されている変更後品の注文とみなされます。この日付より後の既存品(変更前品)の注文は、相互契約により変更前品の在庫状況に応じて履行されます。
現在の材料の最終出荷日:	26 Dec 2021 既存品(変更前品)の最終出荷日は、変更前品の製造および在庫の状況によって変更されることがあります。
製品カテゴリ:	アクティブなコンポーネント - 個別コンポーネント
連絡先情報:	現地のオン・セミコンダクター営業所または Ammar.Anuar@onsemi.com にお問い合わせください。
サンプル:	現地のオン・セミコンダクター営業所に注文するか、また PCN.samples@onsemi.com にお問い合わせください。 サンプルは、この変更通知の発行から 45 日以内に要求してください。 サンプル納入時は、依頼日、数量、特別梱包材/ラベル条件によって異なります。
追加の信頼性データ:	お客さまの地域のオン・セミコンダクター営業所または Robert.Baran@onsemi.com にお問い合わせください。
通知種別:	これは、お客様宛の初回製品 / プロセス変更通知 (IPCN) です。IPCN は、近日中に実施される変更に関する事前通知であり、変更の詳細および影響を受けるデバイスについての一般情報が記載されます。また、暫定的な信頼性認証計画も記載されます。 最終的な認定データおよび特性データは最終製品 / プロセス変更通知 (FPCN) に含まれます。この IPCN は、変更実施から少なくとも 12 か月前に発行される最終製品 / プロセス変更通知 (FPCN) に先だって通知されます。ご不明な点がありましたら PCN.Support@onsemi.com にお問い合わせください。
変更カテゴリ:	変更種別
梱包/出荷	ドライ パック要件の変更
プロセス - ウェハー製造	ウェハー工場の全て / 一部の異なる場所 / 拠点 / 外注への移管 新規ウェハー径
プロセス - 組立	組立の全て / 一部の異なる場所 / 拠点 / 外注への移管, プロセステクノロジー (例えばメッキ), リードフレーム寸法の変更
説明および目的:	<p>本製品変更通知は、オンの自動車用 30V および 40V Trench 6 MOSFET テクノロジー製品のウェハー製造を、米国ニューヨーク州にあるグローバルファンドリー工場に移管することにより、生産能力の拡大を図ることをお知らせするものです。</p> <p>変更は、ウェハー製造、バックグラインドおよびバックメタルのグローバルファウンドリーへの移管、そして 200mm ではなく 300mm 径ウェハーの使用が含まれます。また、組立拠点は変更されませんが(オンセミコンダクター、マレーシアのセレンバン)、300mm 径ウェハーに対応するようにウェハーソーとダイアタッチ設備が更新されています。さらに、以下の表に示すように、側面のめっきの改善とドライパックの廃止のため、ウェットブルフランクリッドフレームの設計とめっき工程が強化されています。</p> <p>オーダー可能な製品番号に変更はありません。</p> <p>本変更の結果として製品マーキングに変更はありません。</p>

	変更前の表記	変更後の表記
ウェハー製造拠点	ON Aizu, Japan ON Gresham, US	<u>Global Foundries, US</u>
ウェハー径	200mm (existing sites)	300mm (Global Foundries)
ウェハープローブ拠点	ON Seremban, Malaysia	<u>Global Foundries, US</u>
バックグランド、バックメタル拠点	ON ISMF, Malaysia	<u>Global Foundries, US</u>
ウェットブルフランクメッキ拠点	Metek, Malaysia (Sub-con)	ON Seremban, Malaysia
リードフレーム設計	1. タイバーはゲートとソースリードに接続して いません 2. アップセットリード設計 3. 標準のフラグサイズ 	1. ゲートとソースリードに接続する追加のタイバー 2. フラットリード設計 3. フラグサイズを大きくする 
クリップ設計	標準	クリップのダウンセット深さの寸法変化(アップセットリードからフラットリード設計への変更による)
側面めっき法	無電解 SN メッキ	電解 SN メッキ
梱包	ドライパック (MSL 1)	ドライパックなし (MSL 1)
ケースアウトライン	濡れない側面との共有	新しいケースの概要
変更の理由 / 動機:	ソース/供給/能力変更プロセス/材料変更	
適合性、形状、機能、信頼性、製品安全性、または製造可能性に関して見込まれる影響	<p>製品は同じ製品仕様に基づいて認定および検証されています。製品は認定試験に正常に合格しています。潜在的な影響が確認される可能性があります。オン・セミコンダクターが PCN に関して実施する検査により、関連するリスクは検証および排除されます。</p> <p>予想される影響はありません。</p>	
影響を受ける拠点:		
オン・セミコンダクター拠点:	外部製造工場 / 下請業者拠点:	
On Semiconductor Gresham, United States	GlobalFoundries, Fab 10, New York, US	
ON Semiconductor Aizu, Japan	Metek Seremban, Malaysia (Subcon)	
ON Semiconductor Seremban, Malaysia		
ON ISMF, Malaysia		



部品の表示 / 変更の追跡可能性:

材料はオンのトレースコードとトラッキングにてトレースできます。

信頼性データの要約:

(QV4) : NVMF55C404NLT1G

RMS : 66099 & 67566

パッケージ: SO8FL-HE

テスト	仕様	条件	間隔
HTRB	JESD22-A108	Ta=150°C, 100% max rated Vds	2016 hrs
HTGB	JESD22-A108	Ta= -150°C, 100% max rated Vgss	2016 hrs
HTSL	JESD22-A103	Ta= 150°C	2016 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off =2 min	30000 cyc
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL1 @ 260°C	
RSH	JESD22- B106	Ta = 265C, 10 sec	

(QV3) : NVMF55C604NLWFT1G

RMS : 67657

パッケージ: SO8FL-HE

テスト	仕様	条件	間隔
HTRB	JESD22-A108	Ta=150°C, 100% max rated Vds	2016 hrs
HTGB	JESD22-A108	Ta= -150°C, 100% max rated Vgss	2016 hrs
HTSL	JESD22-A103	Ta= 150°C	2016 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off =2 min	30000 cyc
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
PC	J-STD-020 JESD-A113	MSL1 @ 260°C	
AC	JESD22-A102	121°C, 100% RH, 15 PSIG	96 hrs
RSH	JESD22- B106	Ta = 265C, 10 sec	
SD	J STD 002	Ta=245C, 5 sec	

(QV5) : NVTFS5C680NLTAG

RMS : 66103

パッケージ: u8F

テスト	仕様	条件	間隔
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL1 @ 260°C	



(QV6) : NVMF55C404NWFT3G-K

RMS : 66100

パッケージ: SO8FL-HE

テスト	仕様	条件	間隔
HTGB	JESD22-A108	Ta= _150°C, 100% max rated Vgss	2016 hrs

認定完了予定日: 27 November 2020

電気的特性の要約:

電気的特性への影響はありません。

影響を受ける部品の一覧:

注: 標準の部品番号(既製品)のみが部品一覧に記載されます。本 PCN に影響を受けるカスタム 部品は、PCN メールのお客様の特定の PCN の付属文書、または PCN カスタマイズポータルに記載されています。

現在の部品番号	新部品番号	認定試験用ピークル
NVMF54C05NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C423NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C456NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G



NVMF55C456NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C456NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C456NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C456NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C460NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C460NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C460NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C460NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C460NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVTF55C453NLWFTAG	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G, NVTF55C680NLTAG
NVTF55C466NLWFTAG	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G, NVTF55C680NLTAG
NVMF54C03NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF54C03NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G



NVMFS4C05NWFT1G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS4C302NWFT1G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVTFS4C05NWFTAG	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G, NVTFS5C680NLTAG
NVTFS4C13NWFTAG	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G, NVTFS5C680NLTAG
NVTFS4C13NWFTWG	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G, NVTFS5C680NLTAG
NVMFS4C01NWFT1G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS4C01NWFT3G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C404NLWFAFT1G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C404NLWFAFT3G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C404NLWFT1G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C404NLWFT3G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C404NWFAFT1G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C404NWFAFT3G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G



NVMFS5C404NWFT1G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C404NWFT1G-K	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C404NWFT1G-M	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C404NWFT3G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C404NWFT3G-K	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C410NLWFAFT1G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C410NLWFAFT3G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C410NLWFT1G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C410NLWFT3G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C410NWFFAFT1G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C410NWFFAFT3G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C410NWFT1G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C410NWFT3G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C410NWFFAFT1G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C410NWFFAFT3G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C410NWFT1G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C410NWFT1G-M	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G
NVMFS5C410NWFT3G	NA	NVMFS5C404NLT1G, NVMFS5C404NWFT3G-K, NVMFS5C604NLWFT1G



NVMF55C423NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C423NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C423NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C426NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C426NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C426NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C426NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C426NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C430NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G



NVMF55C442NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NLWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C442NWFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NLWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NLWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NLWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NWFAFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NWFAFT3G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G
NVMF55C450NWFT1G	NA	NVMF55C404NLT1G, NVMF55C404NWFT3G-K, NVMF55C604NLWFT1G